Revision: 1.0
Date: 7-Feb-05

Statement of Materials, Construction

LEAD-FREE -- 10L MSOP -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.01002250	Cu	7440-50-8	0.00945	38.55956	96.2
				Ni	7440-02-0	0.00029	1.20241	3
				Si	7440-21-3	0.00006	0.26072	0.65
				Mg	7439-95-4	0.00001	0.05998	0.15
				Ag	7440-22-4	0.00020	0.80990	0.13
2	Die	Silicon Chip	0.001611	Si	7440-21-3	0.00161	6.57307	99.95
3	Die attach material	Conductive Epoxy	0.0004251	Epoxy resin (5-25)	Proprietary	0.00006	0.26017	15
				Silver (70-85)	7440-21-3	0.00034	1.37889	79.5
				Aromatic Amine (1-10)	Proprietary	0.00002	0.09540	5.5
4	Wire	Gold	0.000157	Au	7440-57-5	0.00016	0.64051	99.99
5	Lead Finish	Tin	0.000620	Sn	7440-31-5	0.00062	2.52967	100
6	Encapsulation	Epoxy Resin	0.0116735	Fused Silica	60676-86-0	0.01004	40.96115	86
				Epoxy Resin Type A	Proprietary	0.00070	2.85775	6
				Epoxy Resin Type B	Proprietary	0.00018	0.71444	1.5
				Phenol Novalac	9003-35-4	0.00047	1.90517	4
				Antimony trioxide	1309-64-4	0.00018	0.71444	1.5
				Brominated Epoxy Resin	68541-54-0	0.00007	0.28578	0.6
				Carbon Black	1333-86-4	0.00004	0.14289	0.3
Total Package weight			0.02451					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (	aximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys